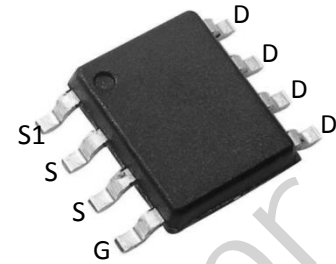


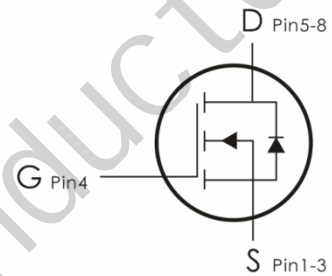
## Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent  $R_{DS(on)}$  with low gate charge. It can be used in a wide variety of applications.



## Features:

- 1)  $V_{DS}=100V, I_D=8A, R_{DS(ON)} < 20m\ \Omega @ V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra  $R_{DS(ON)}$ .
- 5) Excellent package for good heat dissipation.



## Absolute Maximum Ratings: ( $T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current- $T_C=25^\circ C^1$	8	A
	Continuous Drain Current- $T_C=100^\circ C$	---	
	Pulsed Drain Current <sup>2</sup>	30	
$E_{AS}$	Single Pulse Avalanche Energy <sup>5</sup>	28	mJ
$P_D$	Power Dissipation <sup>3</sup>	3.3	W
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

## Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction to Case	---	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction to mbient <sup>4</sup>	38	$^\circ C/W$

**Package Marking and Ordering Information:**

Part NO.	Marking	Package
FDS3672	FDS3672	SOP-8

**Electrical Characteristics:** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units	
<b>Off Characteristics</b>							
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	100	---	---	V	
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=100V$	---	---	1	$\mu\text{A}$	
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	$\pm 100$	nA	
<b>On Characteristics</b>							
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	1.4	---	2.5	V	
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS}=10V, I_D=8A$	---	13.8	20	m $\Omega$	
		$V_{GS}=4.5V, I_D=4A$	---	17.4	26		
<b>Dynamic Characteristics</b>							
$C_{iss}$	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=1\text{MHz}$	---	1000	---	pF	
$C_{oss}$	Output Capacitance		---	180	---		
$C_{rss}$	Reverse Transfer Capacitance		---	9	---		
<b>Switching Characteristics</b>							
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=50V, I_D=5A, R_G=10\ \Omega$	---	16.6	---	ns	
$t_r$	Rise Time		---	3.8	---	ns	
$t_{d(off)}$	Turn-Off Delay Time		$V_{GS}=10V$	---	75.5	---	ns
$t_f$	Fall Time			---	46	---	ns
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V, I_D=5A$	---	16.2	---	nC	
$Q_{gs}$	Gate-Source Charge		---	2.8	---	nC	
$Q_{gd}$	Gate-Drain "Miller" Charge		---	4.1	---	nC	
<b>Drain-Source Diode Characteristics</b>							

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$V_{SD}$	Source-Drain Diode Forward Voltage	$V_{GS}=0V, I_S=8A$	---	---	1.3	V
$I_S$	Continuous Source Current	$V_{GS} < V_{th}$	---	---	8	A
$I_{Sp}$	Pulsed Source Current		---	---	90	
$T_{rr}$	Reverse Recovery Time	$I_S=8 A,$ $di/dt=100 A/\mu s$	---	49	---	NS
$Q_{rr}$	Reverse Recovery Charge		---	61.8	---	BC
$I_{rrm}$	Peak reverse recovery current		---	2.4	---	BC

**Notes:**

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ C$ .
- 5)  $V_{DD}=50 V, R_G=25 \Omega, L=0.3 mH$ , starting  $T_j=25^\circ C$ .

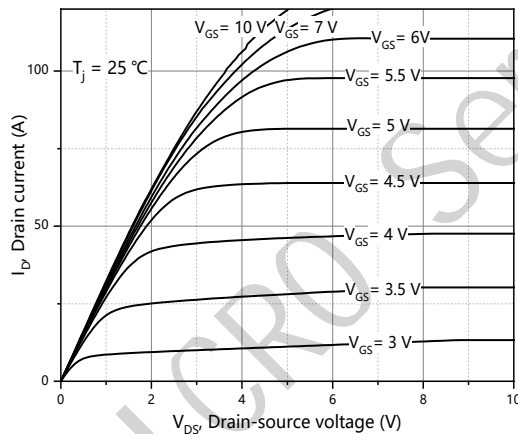
**Typical Characteristics:** ( $T_C=25^\circ C$  unless otherwise noted)


Figure 1, Typ. output characteristics

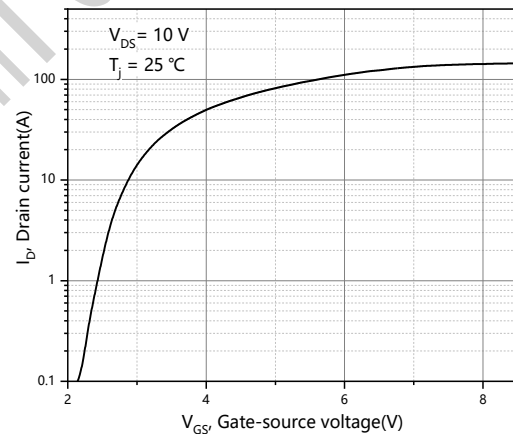


Figure 2, Typ. transfer characteristics

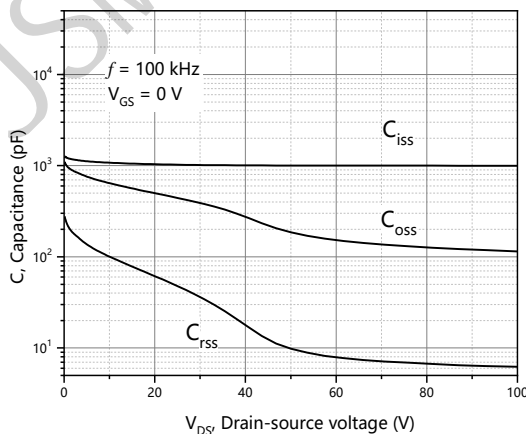


Figure 3, Typ. capacitances

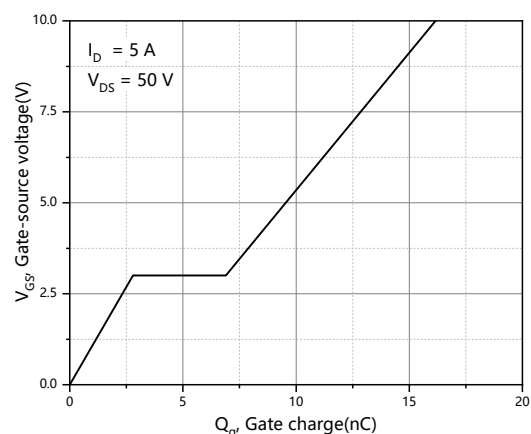


Figure 4, Typ. gate charge

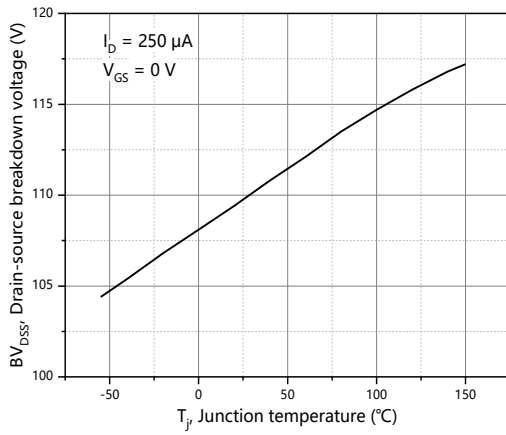


Figure 5, Drain-source breakdown voltage

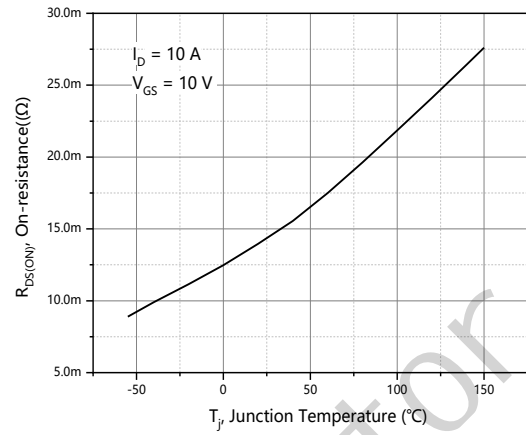


Figure 6, Drain-source on-state resistance

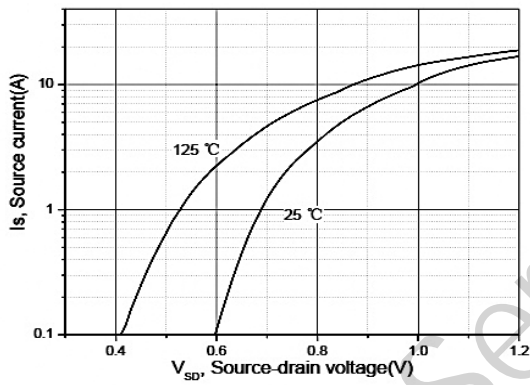


Figure 7, Forward characteristic of body diode

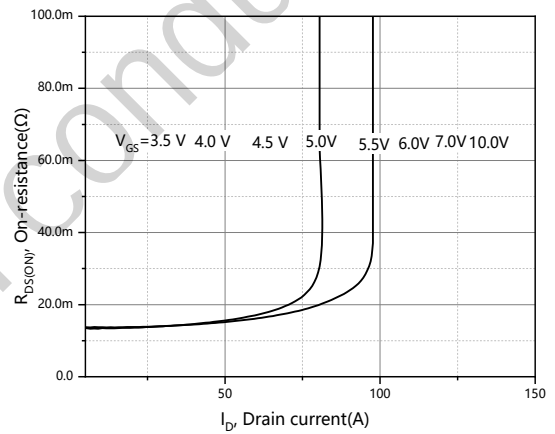


Figure 8, Drain-source on-state resistance

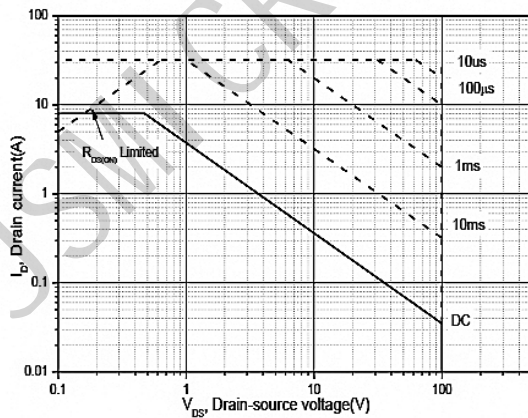
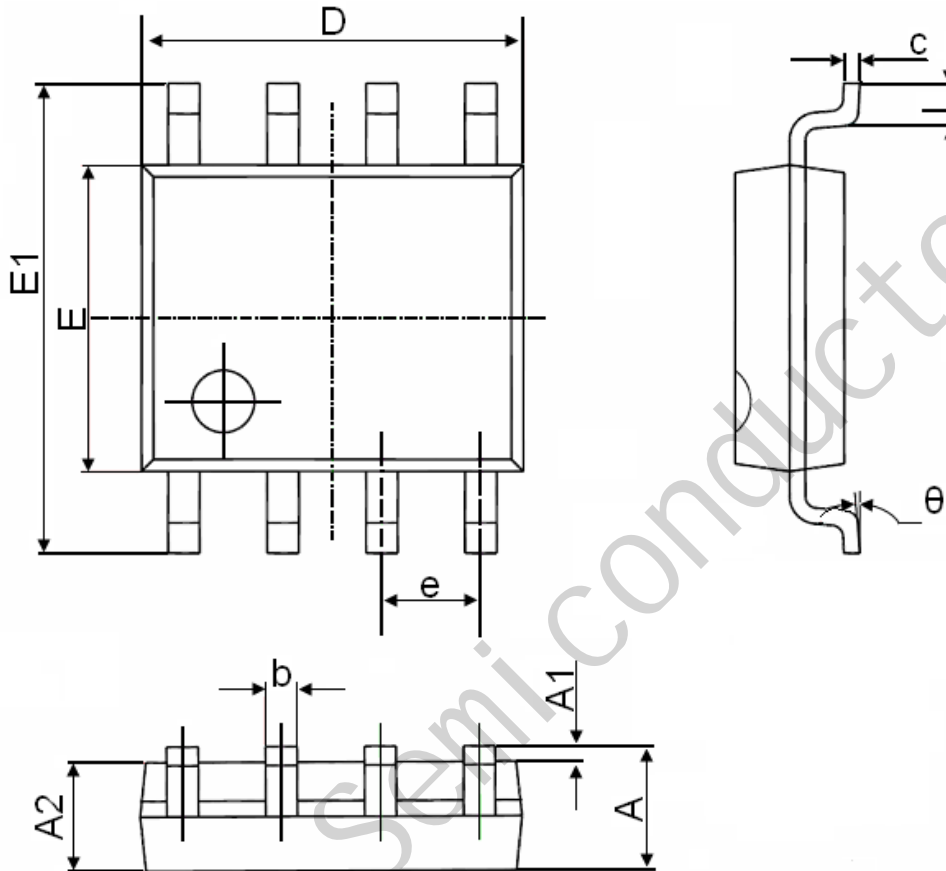


Figure 9 , Safe operation area  $T_C=25\text{ }^\circ\text{C}$

**SOP-8 Package Information**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

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